



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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EL6EEO9S
(DRAWING NO.)

| 版数 REV. | 年月日 DATE | DCN NO. | 変更内容 DESCRIPTION | 製図 DR. | 担当 CHK. | 査閲 APPD. | 承認 APPD. |
|------------|-------------|---------|-----------------------|------------|------------|-------------|-------------|
| 2 | 13.Dec.1999 | 45270 | ADDED ITEM | M.ABE | H.OBIKANE | | H.AMEMIYA |
| 3 | 23.Jun.2000 | 46371 | REVISED FORM | | H.OBIKANE | | H.AMEMIYA |
| 4 | 13.Mar.2001 | 47787 | REVISED TERMINALS No. | H.SAKURADA | H.OBIKANE | | H.AMEMIYA |

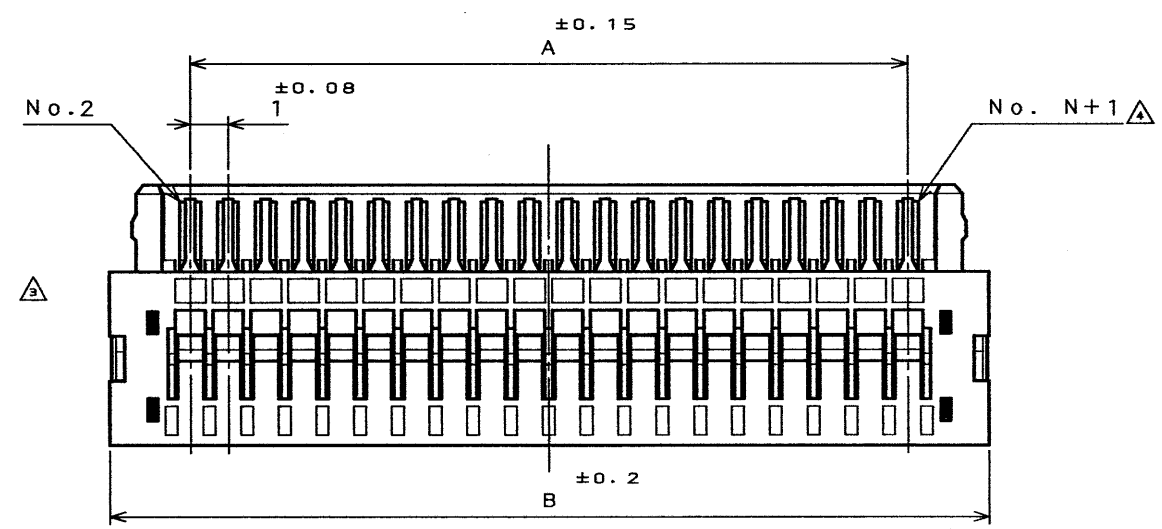
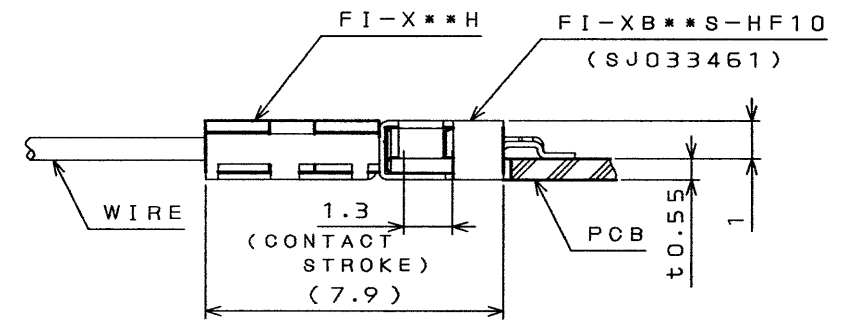
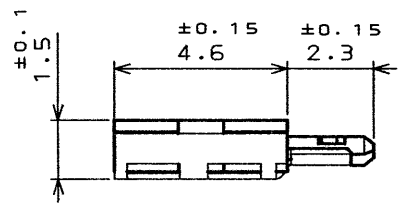
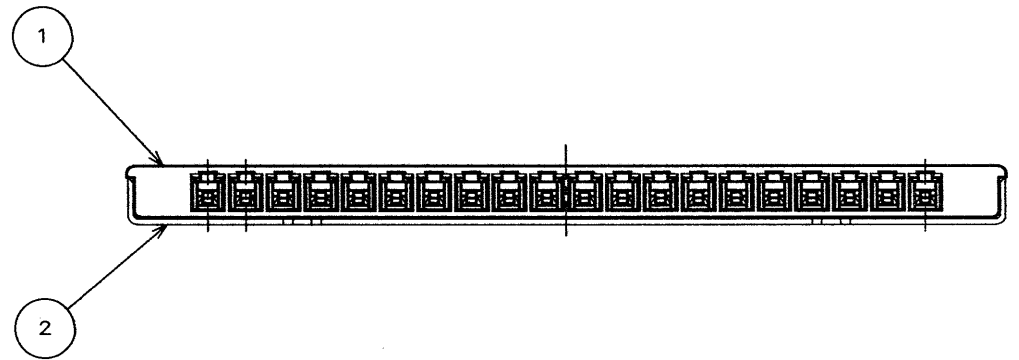
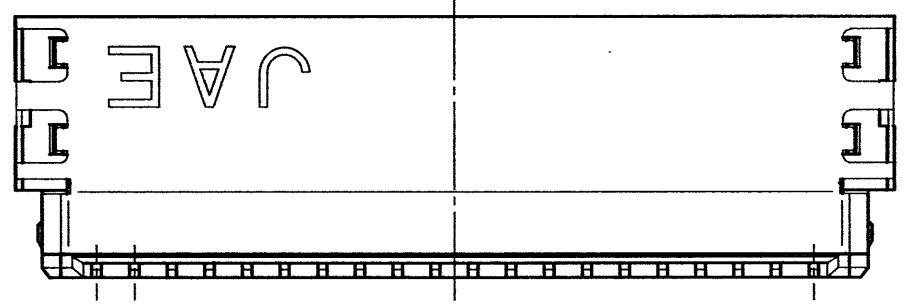


TABLE 1

| DIMENSION NO. OF CONTACTS(N) | A | B |
|---------------------------------|----|------|
| 14 | 13 | 17.3 |
| 20 | 19 | 23.3 |
| 30 | 29 | 33.3 |



MATED CONDITION (REF.)
嵌合状態図(参考)



| | | | | | |
|---|-------------------|-----------------------------------|--------------------------|---|---|
| 2 | SHELL | 1 | COPPER ALLOY | TIN PLATING | |
| 1 | HOUSING | 1 | GLASS FILLED 4-6Ny | | |
| 符号 NO. | 名称 DESCRIPTION | 個数 QTY. | 材料 MATERIAL | 仕上 FINISH | 備考 REMARKS |
| 仕様書 (SPECIFICATION) | | 第1版 (ORIGINAL DATE) 2.Apr.1999 | | 尺取 (SCALE) 5:1 | 日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD. |
| 公差 (GENERAL TOLERANCE) | | 製図 DR. | 担当 CHK. K.HAYASHI | 名称 (TITLE) FI-X**H (HOUSING) 重量 (WEIGHT) | |
| 寸法 (DIMENSION) | | 製図 CHK. K.HISATOMI | 査閲 APPD. H.AMEMIYA | | |
| 角度 (ANGLES) | | 承認 APPD. | | | |
| . ±0.8 .X ±0.4 .XX ±0.1 .XXX ± | | | | | |
| | | | | 図面番号 (DRAWING NO.) SJ033913 | |
| | | | | 版数 (REV.) 4 | |

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